L Number	Hits	Search Text	DB	Time stamp
1	750914	packag$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/10 13:18
2	1067437	lead leadframe (lead near frame)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/10 13:19
3	142691	packag$3 and (lead leadframe (lead near frame))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/10 13:20
5	51746	(packag$3 and (lead leadframe (lead near frame))) and chip	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/10 13:21
7	4365	((packag$3 and (lead leadframe (lead near frame))) and chip) and die near pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/10 13:22
8	2195	(((packag$3 and (lead leadframe (lead near frame))) and chip) and die near pad) and encapsulat$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/10 13:24
9	1673	((((packag$3 and (lead leadframe (lead near frame))) and chip) and die near pad) and encapsulat$3) and (@ad<20010305 @rlad<20010305)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/10 13:26

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